

STACKED MICROELECTRONIC DIES AND METHODS FOR STACKING  
MICROELECTRONIC DIES

ABSTRACT

An assembly of microelectronic devices and method for forming an assembly of microelectronic devices. In one embodiment, the method includes positioning a first packaged microelectronic device adjacent to a support member having support member circuitry, with the first packaged microelectronic device having a first microelectronic die at least partially encased in a first encapsulant to define a first package configuration. The method can further include electrically connecting the first packaged microelectronic device to a first portion of the support member circuitry and positioning at least proximate to the first packaged microelectronic device a second packaged microelectronic device having a second microelectronic die at least partially encased in a second encapsulant to define a second package configuration different than the first package configuration. The first packaged microelectronic device can be positioned between the support member and the second packaged microelectronic device. The second packaged device can be coupled directly to a second portion of the support member circuitry. Accordingly, the second packaged microelectronic device can be connected directly to the support member without connecting the second packaged device to the first packaged device.